Engineering Development Model

RF Transformer

TX-ED8345/4

Impedance Ratio: 1

Important Note

This model has been designed, built and tested in our engineering department. Performance data represents model capability. At present it is a non-catalog model. On request, we can supply a final specification sheet, part number and price/delivery information.



Please click "Back", and then click "Contact Us" for Applications support.

CASE STYLE: TT240

ELECTRICAL SPECIFICATIONS 50Ω @ +25°C					
Parameter Min. Typ. Max. Uni					Units
Frequency		0.3		400	MHz
Insertion Loss *	3 dB Bandwidth		0.3 - 400		MHz
	2 dB Bandwidth		0.3 - 350		MHz
	1 dB Bandwidth		0.3 - 250		MHz

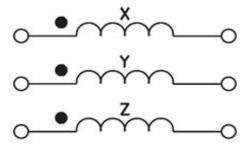
Note:

^{*} Insertion Loss is referenced to mid-band loss, 0.31dB typ.

MAXIMUM RATINGS				
Operating Temperature -20°C to 85°C				
Storage Temperature	-55°C to 100°C			
RF Power	0.25 W			
DC Current	30 mA			

DC Current	30 IIIA			
PIN CONNECTIONS				
PRIMARY DOT X1 Y2 Z3				
PRIMARY	X6 Y5 Z4			

Configuration: F

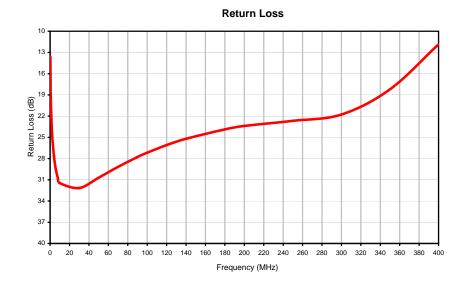


Typical Performance Data

FREQUENCY (MHz)	INSERTION LOSS (dB)	RETURN LOSS (dB)	
0.30	0.80	13.65	
0.50	0.66	16.97	
0.70	0.60	18.90	
0.90	0.56	20.24	
2.00	0.42	24.30	
4.00	0.35	27.72	
6.00	0.33	29.58	
8.00	0.32	30.73	
10.00	0.31	31.46	
30.00	0.35	32.16	
50.00	0.38	30.71	
70.00	0.42	29.17	
90.00	0.42	27.78	
100.00	0.45	27.17	
120.00	0.51	26.09	
140.00	0.51	25.20	
180.00	0.51	23.88	
200.00	0.63	23.39	
250.00	0.65	22.66	
300.00	0.84	21.77	
350.00	1.01	18.21	
400.00	1.76	11.86	

Typical Performance Curves

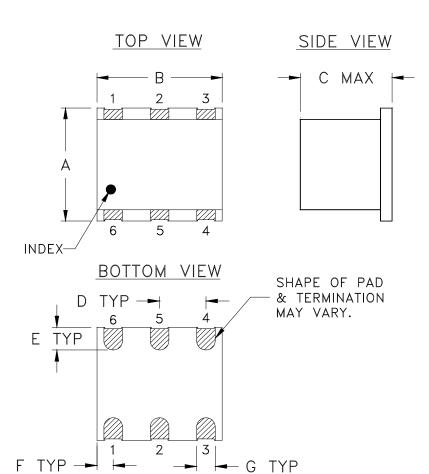




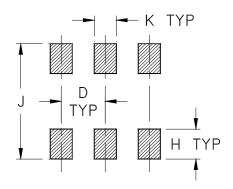
Case Style

TT240

Outline Dimensions



PCB Land Pattern



Suggested Layout, Tolerance to be within ±.002

CASE #	A	В	С	D	Е	F	G	Н	J	K	WT. GRAM
TT240	.250 (6.35)	.31 (7.87)	.20 (5.08)	.100 (2.54)	.050 (1.27)	.055 (1.40)	.040 (1.02)	.070 (1.78)	.270 (6.86)	.050 (1.27)	.50

Dimensions are in inches (mm). Tolerances: 2Pl. ± .01; 3 Pl. ± .005

Notes:

- 1. Case material: Ceramic.
- 2. Termination finish:

For RoHS Case Styles: 2-10μ inch (.05-.25 microns) Gold plate over 100-300 μ inch (2.54-7.62 microns) Nickel plate.

All models, (+) suffix.

For RoHS-5 Case Styles: Tin-Lead plate. All models, no (+) suffix.





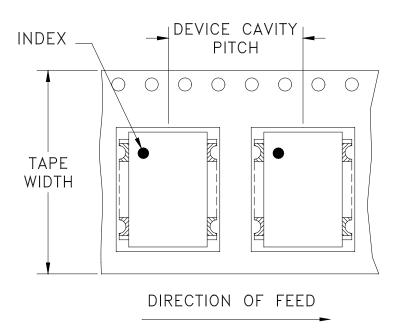
P.O. Box 350166, Brooklyn, New York 11235-0003 (718) 934-4500 Fax (718) 332-4661 For detailed performance specs & shopping online see Mini-Circuits web site



RF/IF MICROWAVE COMPONENTS

Tape & Reel Packaging TR-F2

DEVICE ORIENTATION IN T&R



Tape Width, mm	Device Cavity Pitch, mm	Reel Size, inches	Devices per Reel See note
			10
			20
16	12	7	50
			100
			200
		13	500
			1000

Mini-Circuits carrier tape materials provide protection from ESD (Electro-Static Discharge) during handling and transportation. Tapes are static dissipative and comply with industry standards EIA-481/EIA-541.

Go to: www.minicircuits.com/pages/pdfs/tape.pdf



Mini-Circuits ISO 9001 & ISO 14001 Certified



Environmental Specifications

ENV02

All Mini-Circuits products are manufactured under exacting quality assurance and control standards, and are capable of meeting published specifications after being subjected to any or all of the following physical and environmental test.

Specification	Test/Inspection Condition	Reference/Spec
Operating Temperature	-20° to 85°C Ambient Environment	Individual Model Data Sheet
Storage Temperature	-55° to 100° C Ambient Environment	Individual Model Data Sheet
Humidity	90 to 95% RH, 240 hours, 50°C	MIL-STD-202, Method 103, Condition A, Except 50°C and end-point electrical test done within 12 hours
Thermal Shock	-55° to 100°C, 100 cycles	MIL-STD-202, Method 107, Condition A-3, except +100°C
Solder Reflow Heat	Sn-Pb Eutetic Process: 225°C peak Pb-Free Process 245° - 250°C peak	J-STD-020, Table 4-1, 4-2 and 5-2, Figure 5-1
Solderability	10X Magnification	J-STD-002, 95% Coverage
Vibration (High Frequency)	20g peak, 10-2000 Hz, 12 times in each of three perpendicular directions (total 36)	MIL-STD-202, Method 204, Condition D
Mechanical Shock	50g, 11 ms, 1/2-sine, 18 shocks: 3 each direction, each of 3 axes	MIL-STD-202, Method 213, Condition A
Marking Resistance to Solvents	Isopropyl alcohol + mineral spirits at 25°C; terpene defluxer at 25°C; distilled water + proylene glycol monomethyl ether + monoethanolamine at 63°C to 70°C	MIL-STD-202, Method 215

ENV02 Rev: A

02/25/11

M130240 File: ENV02.pdf

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